IN THE CLAIMS:

Please amend claim 5, cancel claims 1-4 and 8-9 without prejudice or disclaimer, and add new claims 10-17 as follows. This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-4 (canceled).

Claim 5 (Currently Amended): A multilayer printed wiring board comprising a substrate, a plated through-hole, [[the]] a solvent-free filling material ~~according to claim 1~~ filling the plated through-hole, and a conductor layer formed on an exposed surface of the filling material in the plated through-hole,

wherein the filling material includes a filler, a thermosetting resin, a curing agent, and a curing catalyst, the thermosetting resin being an epoxy resin, the curing agent being a dicyandiamide curing agent.

Claim 6 (Original): The multilayer printed wiring board according to claim 5, which further comprises: an insulating layer formed on a surface of the conductor layer; a conductor pattern layer formed on a surface of the insulating layer so that the conductor layer, the insulating layer and conductor pattern layer are provided in this order; and a via conductor which electrically connects the conductor layer and the conductor pattern layer.

Claim 7 (Original): The multilayer printed wiring board according to claim 5, wherein the plated through-hole has a diameter of 200 μm or smaller.

Claims 8-9 (Canceled).

Claim 10 (New): The multilayer printed wiring board according to claim 5, wherein the curing catalyst comprises a urea compound.

Claim 11 (New): The multilayer printed wiring board according to claim 10, wherein the urea compound is a material selected from the ground consisting of dimethylurea compound, aromatic urea compound, alicyclic urea compound and hologenated urea compound.

Claim 12 (New): The multilayer printed wiring board according to claim 10, wherein the urea compound is a material selected from the ground consisting of dimethylurea compound, aromatic urea compound and alicyclic urea compound.

Claim 13 (New): The multilayer printed wiring board according to claim 5, wherein the dicyandiamide curing agent has at least one form selected from the group consisting of powders, dendrites, and flakes.

Claim 14 (New): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 0.1 to 100 μm.

Claim 15 (New): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 1 to 30 μm.

Claim 16 (New): The multilayer printed wiring board according to claim 13, wherein the dicyandiamide curing agent is powder having an average particle size of 1 to 15 μm.

Claim 17 (New): The multilayer printed wiring board according to claim 5, wherein the filler is substantially spherical particles having an average particle size of 0.1 to 12 μm and a maximum particle size of 75 μm or smaller.